



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

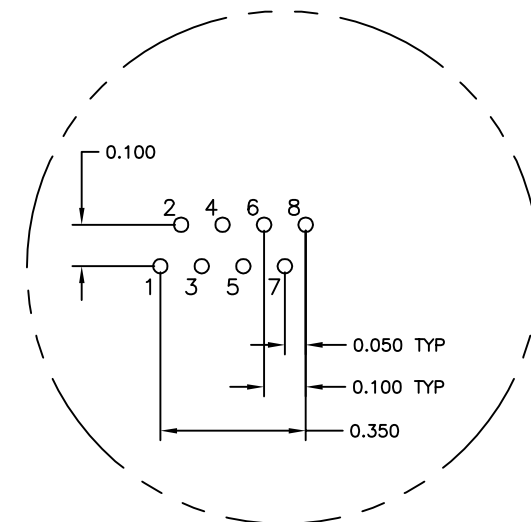
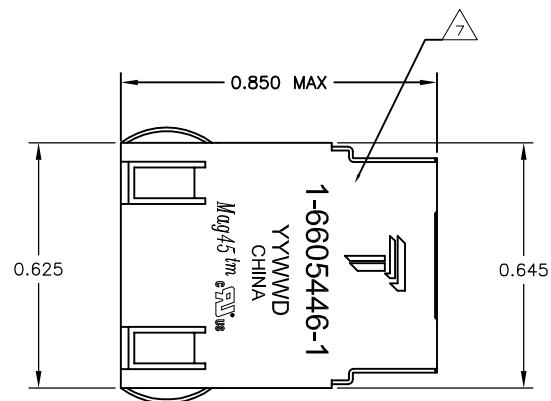
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS					
#	DATE	DESCRIPTION	BY	CHK	APP'D
F	23APR2013	LOGO CHANGE	JC	KZ	

MECHANICAL:



Pin Designations

△ HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0. SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER. MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP. LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80µINCH SILVER OVER 40µINCH NICKEL UNDERPLATE OVER 40µINCH COPPER UNDERPLATE. POST-PLATED WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

△ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

△ MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP: CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

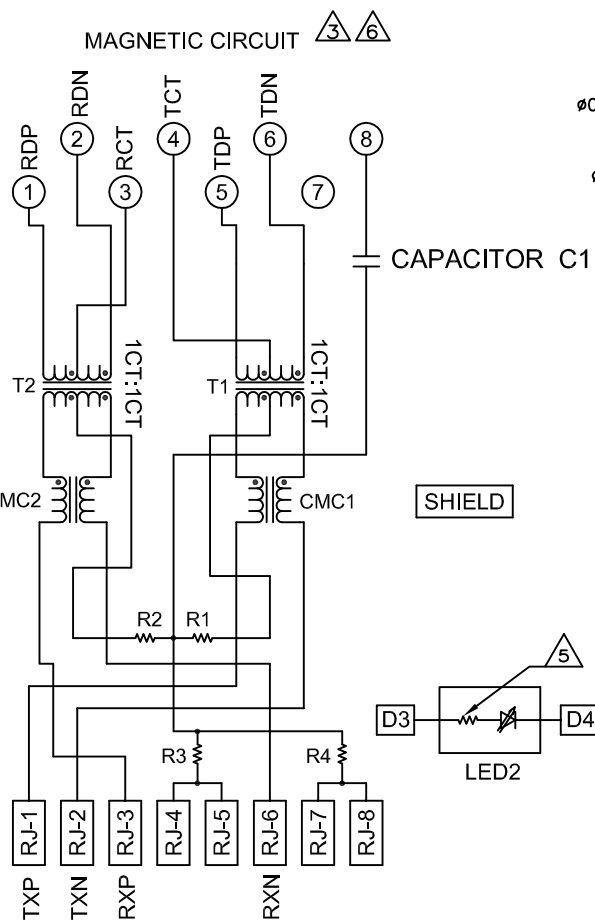
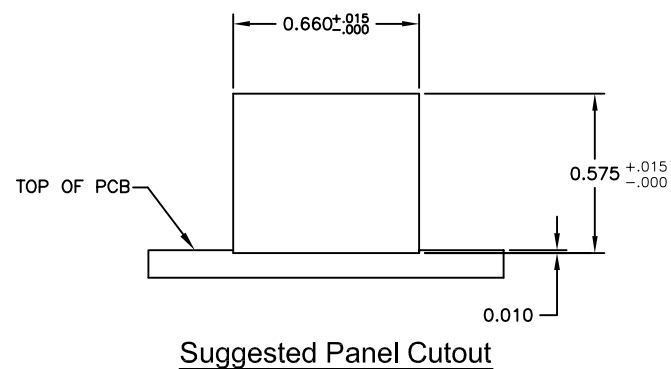
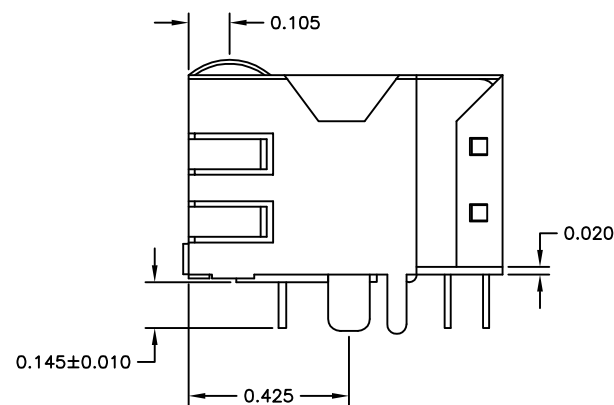
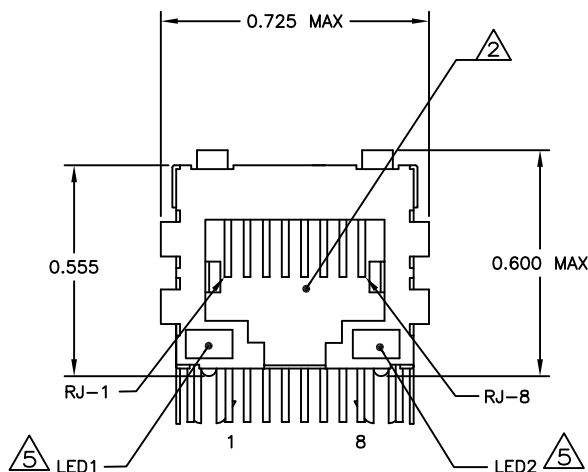
4. OPERATING TEMPERATURE: FROM -40°C - +85°C

△ LEDS WITH BUILT-IN RESISTOR
 LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA. LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ VF=5V
 FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V

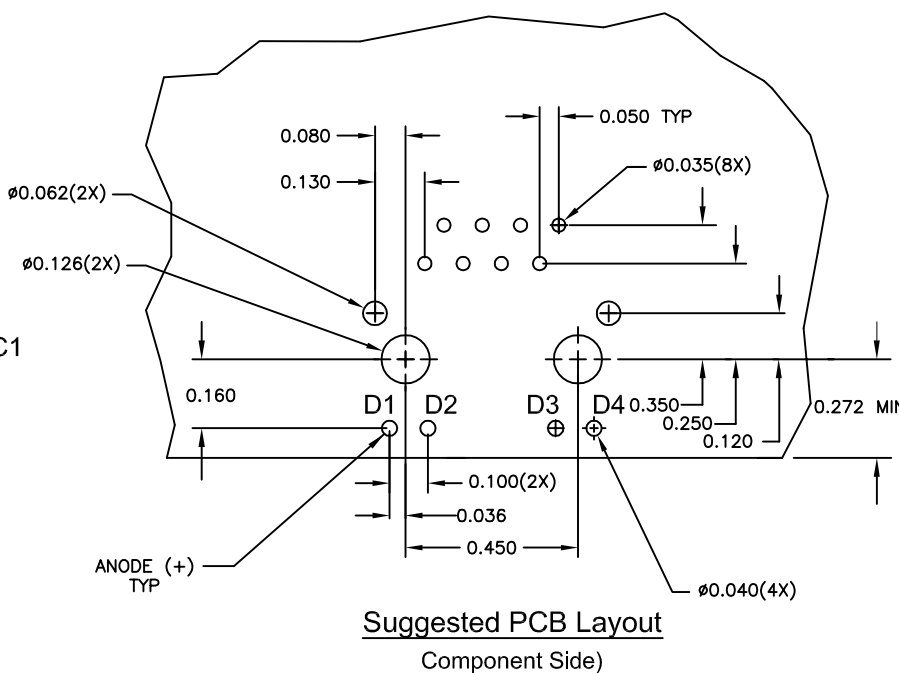
△ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.

△ TRP CONNECTOR LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.



C1= 1000pF, 2KV, CAPACITOR
 R1-R4 = 75 OHMS, 1/16 W RESISTORS



WITH	GREEN	GREEN	6605446-1
WITHOUT	GREEN	GREEN	1-6605446-1
CAPACITOR C1	LED1	LED2	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN: A. FERNANDEZ-DOCKES CHK: D. FAROLE APP'D: D. FAROLE	TRP connector Dongguan China
DIMENSIONS: INCHES	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± .010 2 PLC ± .005 3 PLC ± .005 4 PLC ± .005 ANGLES ± -	PRODUCT SPEC: 108-2100 APPLICATION SPEC: -	SIZE: A1 SCALE: NTS
MATERIAL: 1	FINISH: 1	WEIGHT: -	RESTRICTED TO: -
CUSTOMER DRAWING		C=6605446	SHEET 1 OF 1 REV F